



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-08-31
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Floriana San Biagio	<b>Representative Title</b>	AMG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	9F8W*LL02FC1	A	Z8GA	2016-08-31
Amount	UoM	Unit type	ST ECOPACK Grade	
480.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
ating is used or other bulk terminati	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DIP	9.05X6.4X3.32	8	Through-hole	
Comment	Package: PDIP 08 .3 CU .25 Au W.; MDF valid for MC34063ACN			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	9F8W*LL02FC1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.291	mg	supplier	die	Silicon (Si)	7440-21-3		3.216	mg	977211	6700
				supplier	metallization	Aluminium (Al)	7429-90-5		0.041	mg	12458	85
				supplier	Passivation	Silicon Nitride	12033-89-5		0.014	mg	4254	29
				supplier	Passivation	Silicon Oxide	7631-86-9		0.020	mg	6077	42
Leadframe	Copper & its alloys	186.665	mg	supplier	alloy	Copper (Cu)	7440-50-8		180.029	mg	964450	375060
				supplier	alloy	Iron (Fe)	7439-89-6		3.864	mg	20700	8050
				supplier	alloy	Phosphorus (P)	12185-10-3		0.028	mg	150	58
				supplier	alloy	Zinc (Zn)	7440-66-6		0.092	mg	493	192
				supplier	metallization	Silver (Ag)	7440-22-4		2.652	mg	14207	5525
Die attach	Other organic materials	0.745	mg	supplier	glue	Silver (Ag)	7440-22-4		0.529	mg	710067	1102
				supplier	glue	epoxy resin	Proprietary		0.112	mg	150336	233
				supplier	glue	2,6-Diglycidyl phenyl allyl ether	EC 417-470-1		0.060	mg	80537	125
				supplier	glue	Epoxy resin modifier	Proprietary		0.022	mg	29530	46
Bonding wires	Other organic materials	0.093	mg	supplier	glue	amine compound	Proprietary		0.022	mg	29530	46
				supplier	wire	Copper (Cu)	7440-50-8		0.093	mg	1000000	194
Encapsulation	Other organic materials	286.080	mg	supplier	mold compound	Silica, vitreous	60676-86-0		248.889	mg	869998	518519
				supplier	mold compound	Epoxy resin	25068-38-6		28.608	mg	100000	59600
				supplier	mold compound	Phenol resin	29690-82-2		7.152	mg	25000	14900
				supplier	mold compound	Carbon Black	1333-86-4		1.431	mg	5002	2981
connections coating	Solder	3.125	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.125	mg	1000000	6510